# same sky

## MODEL: HSE13-254225P | DESCRIPTION: HEAT SINK

### FEATURES

• TO-220 package
• bolt on attachment
• pins for secure PCB attachment
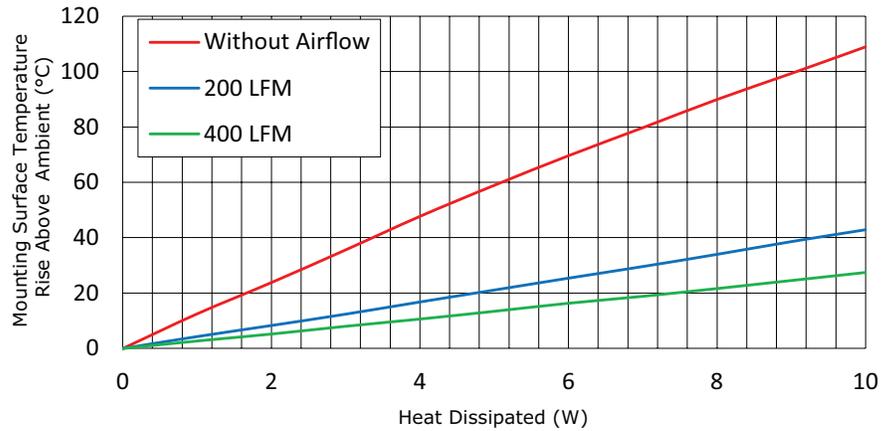• aluminum alloy

RoHS

## MODEL

| MODEL | thermal resistance[1] | | | | power dissipation[1] |
| | @ 75°C ΔT, nat conv [°C/W] | @ 1 W, nat conv [°C/W] | @ 1 W, 200 LFM [°C/W] | @ 1 W, 400 LFM [°C/W] | @ 75°C ΔT, nat conv [W] |
|---|---|---|---|---|---|
| HSE13-254225P | 11.47 | 12.5 | 4.3 | 2.7 | 6.54 |

Note:        1.  See performance curves for full thermal resistance details.

## PERFORMANCE CURVES

| | Heatsink Temperature Rise Above Ambient (ΔT = Ths - Ta) [°C] | | |
|---|---|---|---|
| Power [W] | Natural Conv. | 200 LFM | 400 LFM |
| 0 | 0 | 0 | 0 |
| 1 | 12.5 | 4.3 | 2.7 |
| 2 | 23.8 | 8.3 | 5.2 |
| 3 | 35.6 | 12.4 | 8.0 |
| 4 | 47.7 | 16.8 | 10.6 |
| 5 | 58.9 | 21.1 | 13.4 |
| 6 | 69.6 | 25.4 | 16.3 |
| 7 | 79.7 | 29.6 | 18.8 |
| 8 | 89.9 | 34.0 | 21.6 |
| 9 | 99.3 | 38.6 | 24.5 |
| 10 | 108.9 | 42.9 | 27.4 |

Ths: "hot spot" temperature measured on the heatsink
Ta: ambient temperature



Performance curve chart: Mounting Surface Temperature Rise Above Ambient (°C) vs Heat Dissipated (W), showing Without Airflow (red), 200 LFM (blue), and 400 LFM (green).

# MECHANICAL DRAWING

units: mm
tolerance: ±0.50 mm

| MATERIAL | AL 6063-T5 |
| --- | --- |
| FINISH | black anodized |
| PIN MATERIAL | steel |
| PIN PLATING | 2~3 µm tin |
| WEIGHT | 19.3 g |
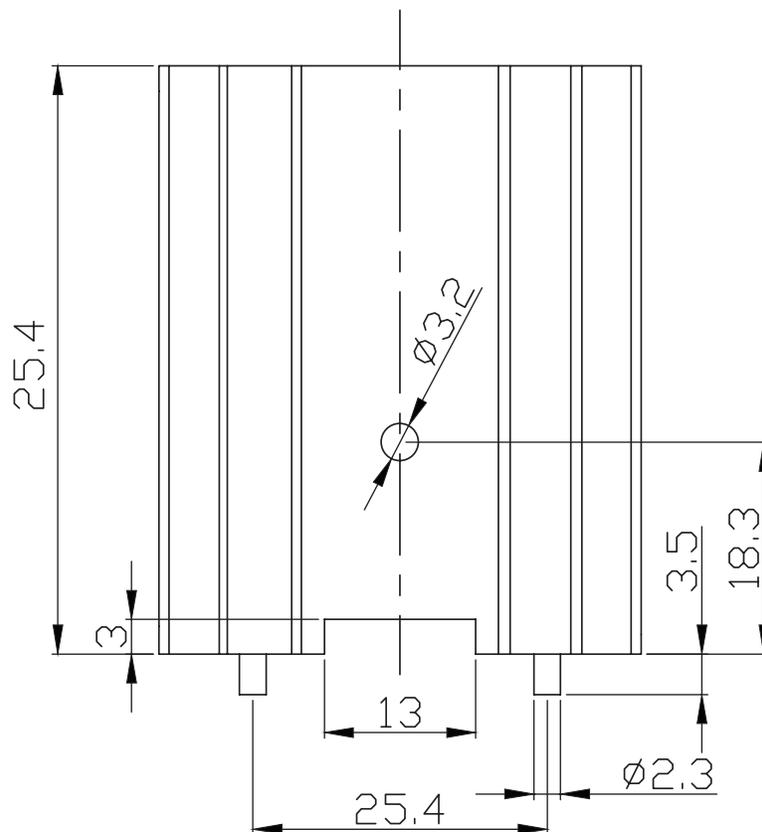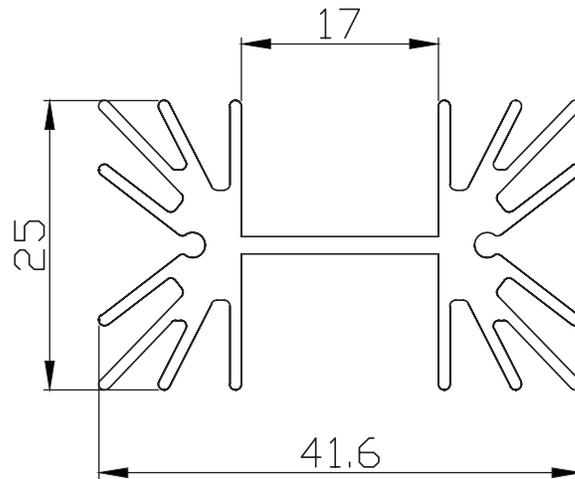
## REVISION HISTORY

| rev. | description | date |
|------|-------------|------|
| 1.0 | initial release | 03/03/2025 |

The revision history provided is for informational purposes only and is believed to be accurate.